

DIMENSIONS: MILLIMETERS *For additional information on our Pb-Free strategy and soldering **DATE 31 OCT 2006**

NOTES:

- DIMENSIONING AND TOLERANCING PER
- COPLANARITY APPLIES TO THE EXPOSED
- PAD AS WELL AS THE TERMINALS.

	MILLIMETERS	
DIM	MIN	MAX
Α	0.70	0.80
A1	0.00	0.05
А3	0.20 REF	
b	0.20	0.30
D	4.00 BSC	
D2	3.20	3.40
E	3.00 BSC	
E2	1.60	1.80
е	0.50 BSC	
K	0.20	
L	0.30	0.50

GENERIC MARKING DIAGRAM*



= Specific Device Code XXXXX = Assembly Location Α = Year WW = Work Week

= Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part

Pb-Free indicator, "G" or microdot " ■", may or may not be present.

To additional information out to Tree strategy and soldering
details, please download the ON Semiconductor Soldering and
Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION: WDFN12, 3X4X0.75, 0.5 P **PAGE 1 OF 1**

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0.50 PITCH

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